

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Xianbin Wang</td> <td>08/25/2006</td> </tr> <tr> <td>Juan Boon Tan</td> <td>08/25/2006</td> </tr> <tr> <td>Liang-Choo Hsia</td> <td>08/30/2006</td> </tr> <tr> <td>Teck Jung Tang</td> <td>08/30/2006</td> </tr> <tr> <td>Huang Liu</td> <td>08/25/2006</td> </tr> </tbody> </table>		Name	Execution Date	Xianbin Wang	08/25/2006	Juan Boon Tan	08/25/2006	Liang-Choo Hsia	08/30/2006	Teck Jung Tang	08/30/2006	Huang Liu	08/25/2006
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RECEIVING PARTY DATA													
Name:	CHARTERED SEMICONDUCTOR MANUFACTURING LTD.												
Street Address:	60 Woodlands Industrial Park D												
Internal Address:	Street 2												
City:	Singapore 738406												
State/Country:	SINGAPORE												
PROPERTY NUMBERS Total: 1													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11558342</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11558342								
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CORRESPONDENCE DATA													
Fax Number:	(408)738-0881												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone:	408-738-0592												
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Correspondent Name:	Mikio Ishimaru												
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Address Line 4:	Sunnyvale, CALIFORNIA 94087												
ATTORNEY DOCKET NUMBER:	1016-075 (CS2005/042)												
NAME OF SUBMITTER:	Mikio Ishimaru												

CH \$40.00 11558342

Total Attachments: 6

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ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

INTEGRATED CIRCUIT PROCESSING SYSTEM

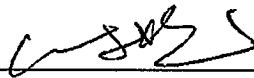
for which a United States patent application has been executed on or before the date of this assignment.

WHEREAS, CHARTERED SEMICONDUCTOR MANUFACTURING LTD., a Corporation of the Republic of Singapore, having a place of business at 60 Woodlands Industrial Park D, Street 2, Singapore 738406, Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted, in the United States and foreign countries.

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

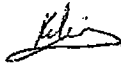
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



Xianbin Wang

Aug. 25, 2006

Date




Witness Signature



Witness Signature

KOO CHEE KIONG

Print Witness Name



Print Witness Name

25 AUG 2006

Date

25. Aug 2006.

Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

JBT

Juan Boon Tan

25 Aug 06

Date

[Signature]

Witness Signature

[Signature]

Witness Signature

KOO CHSE KIANG

Print Witness Name

EE YONG CHIAN G

Print Witness Name

25 AUG 2006

Date

25 August 2006

Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



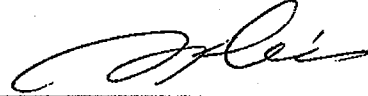
Liang-Choo Hsia

30 Aug. 06

Date

x 

Witness Signature



Witness Signature

x CONF HAI

Print Witness Name

LIU JIN PING

Print Witness Name

x 20 Aug. 06

Date

30 Aug. 06

Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Tang Jung Tang
Teck Jung Tang

30 Aug 2006
Date

X ellu
Witness Signature

[Signature]
Witness Signature

X CONG HAI
Print Witness Name

LIU JIN PING
Print Witness Name

X Aug 30, 06
Date

30 Aug 2006
Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

HL
Huang Liu

15/08/2006
Date

[Signature]
Witness Signature

[Signature]
Witness Signature

KOO CHEE KIONG
Print Witness Name

EE YONG CHIANG
Print Witness Name

25 AUG 2006
Date

25 August 2006.
Date